

### 670MHz Low Noise Amplifiers

The 5962-0623601QPC and 5962-0623602QPC are fully DSCC SMD compliant parts and the SMD data sheets are available on the DSCC website (<http://www.dscc.dla.mil/programs/specfind/default.asp>). The 5962-0623601QPC is electrically equivalent to the EL5132 and the 5962-0623602QPC is electrically equivalent to the EL5133, reference these data sheets for additional information.

These amplifiers are ultra-low voltage noise, high speed, low power consumption voltage feedback amplifiers.

Both amplifiers are stable at gains as low as 10. Not only do these devices find perfect application in high gain applications, they maintain their performance down to lower gain settings.

These amplifiers are available in SBDIP packages. All parts are specified for operation over the -55°C to +125°C temperature range.

### Ordering Information

PART NUMBER	PART MARKING	TEMP (°C)	PACKAGE	PKG. DWG. #
5962-0623601QPC	5962-0623601QPC	-55 to +125	8 Ld SBDIP	D8.3
5962-0623602QPC	5962-0623602QPC	-55 to +125	8 Ld SBDIP	D8.3

### Features

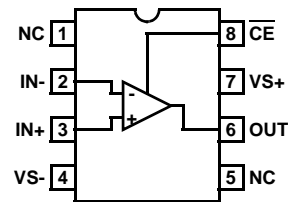
- 670MHz -3dB bandwidth
- Ultra low noise 0.9nV/√Hz
- 1000V/μs slew rate
- Low supply current = 16mA
- Single supplies from 5V to 12V
- Dual supplies from ±2.5V to ±6V
- Fast disable on the 5962-0623601QPC

### Applications

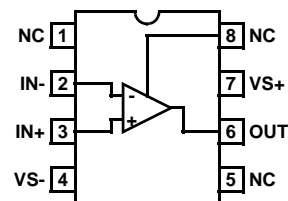
- Pre-amplifier
- Receiver
- Filter
- IF and baseband amplifier
- ADC drivers
- DAC buffers
- Instrumentation
- Communications devices.

### Pinouts

**5962-0623601QPC  
(8 LD SBDIP)  
TOP VIEW**



**5962-0623602QPC  
(8 LD SBDIP)  
TOP VIEW**



## 5962-0623601QPC, 5962-0623602QPC

### Absolute Maximum Ratings ( $T_A = +25^\circ\text{C}$ )

Supply Voltage from $V_{S+}$ to $V_{S-}$ .....	13.2V
Slewrate between $V_{S+}$ and $V_{S-}$ .....	1V/ $\mu\text{s}$
$I_{IN-}$ , $I_{IN+}$ , CE .....	$\pm 5\text{mA}$
Continuous Output Current .....	20mA

### Thermal Information

Storage Temperature .....	$-65^\circ\text{C}$ to $+150^\circ\text{C}$
Ambient Operating Temperature .....	$-55^\circ\text{C}$ to $+125^\circ\text{C}$
Operating Junction Temperature .....	$+150^\circ\text{C}$
Power Dissipation .....	192mW

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

**IMPORTANT NOTE:** All parameters having Min/Max specifications are guaranteed. Typical values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore:  $T_J = T_C = T_A$

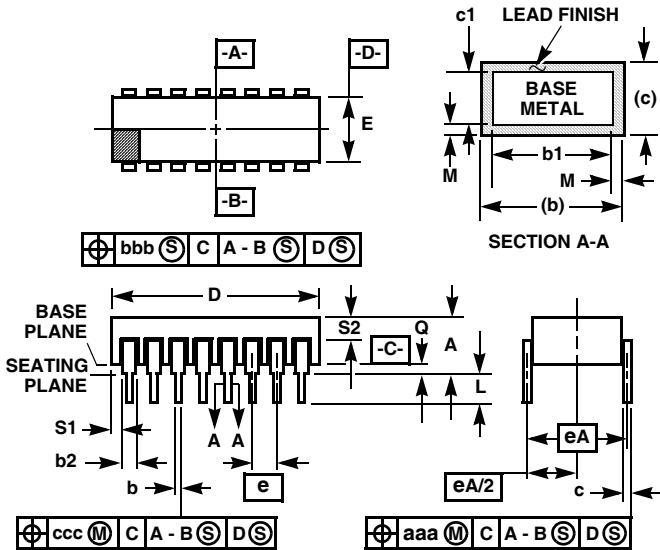
### Electrical Specifications $V_{S+} = +5\text{V}$ , $V_{S-} = -5\text{V}$ , $R_L = 500\Omega$ , $R_F = 10\text{k}\Omega$ , $R_G = 100\Omega$ , $T_A = +25^\circ\text{C}$ , unless otherwise specified.

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
$R_{IN}$	Input Resistance	Common mode		5		$\text{M}\Omega$
$C_{IN}$	Input Capacitance			2		pF
BW	-3dB Bandwidth	$R_F = 225\Omega$ , $A_V = +10$ , $R_L = 1\text{k}\Omega$		670		MHz
BW	$\pm 0.1\text{dB}$ Bandwidth	$R_F = 225\Omega$ , $A_V = +10$ , $R_L = 1\text{k}\Omega$		90		MHz
GBWP	Gain Bandwidth Product			3000		MHz
PM	Phase Margin	$R_L = 1\text{k}\Omega$ , $C_L = 6\text{pF}$		55		$^\circ$
SR	Slew Rate	$R_L = 100\Omega$ , $V_{OUT} = \pm 2.5\text{V}$		1000		V/ $\mu\text{s}$
$t_R$ , $t_F$	Rise Time, Fall Time	$\pm 0.1V_{STEP}$		2.0		ns
OS	Overshoot	$\pm 0.1V_{STEP}$		10		%
$t_S$	0.01% Settling Time			6.6		ns
dG	Differential Gain	$R_F = 1\text{k}\Omega$ , $R_{LOAD} = 150\Omega$		0.01		%
dP	Differential Phase	$R_F = 1\text{k}\Omega$ , $R_{LOAD} = 150\Omega$		0.01		$^\circ$
$e_N$	Input Noise Voltage	$f = 10\text{kHz}$		0.9		nV/ $\sqrt{\text{Hz}}$
$i_N$	Input Noise Current	$f = 10\text{kHz}$		3.5		pA/ $\sqrt{\text{Hz}}$
<b>ENABLE (5962-0623601QPC Only)</b>						
$t_{EN}$	Enable Time			220		nS
$t_{DIS}$	Disable Time			175		nS

### Pin Descriptions

PART		PIN NAME	FUNCTION
5962-0623601QPC	5962-0623602QPC		
1, 5	1, 5, 8	NC	Not connected
2	2	IN-	Inverting input
3	3	IN+	Non-inverting input
4	4	VS-	Negative power supply
6	6	OUT	Amplifier output
7	7	VS+	Positive power supply
8		$\overline{\text{CE}}$	Enable and disable input

Ceramic Dual-In-Line Metal Seal Packages (SBDIP)



D8.3 MIL-STD-1835 CDIP2-T8 (D-4, CONFIGURATION C)  
8 LEAD CERAMIC DUAL-IN-LINE METAL SEAL PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.200	-	5.08	-
b	0.014	0.026	0.36	0.66	2
b1	0.014	0.023	0.36	0.58	3
b2	0.045	0.065	1.14	1.65	-
b3	0.023	0.045	0.58	1.14	4
c	0.008	0.018	0.20	0.46	2
c1	0.008	0.015	0.20	0.38	3
D	-	0.405	-	10.29	-
E	0.220	0.310	5.59	7.87	-
e	0.100 BSC		2.54 BSC		-
eA	0.300 BSC		7.62 BSC		-
eA/2	0.150 BSC		3.81 BSC		-
L	0.125	0.200	3.18	5.08	-
Q	0.015	0.060	0.38	1.52	5
S1	0.005	-	0.13	-	6
S2	0.005	-	0.13	-	7
$\alpha$	90°	105°	90°	105°	-
aaa	-	0.015	-	0.38	-
bbb	-	0.030	-	0.76	-
ccc	-	0.010	-	0.25	-
M	-	0.0015	-	0.038	2
N	8		8		8

NOTES:

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
2. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
3. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness.
4. Corner leads (1, N, N/2, and N/2+1) may be configured with a partial lead paddle. For this configuration dimension b3 replaces dimension b2.
5. Dimension Q shall be measured from the seating plane to the base plane.
6. Measure dimension S1 at all four corners.
7. Measure dimension S2 from the top of the ceramic body to the nearest metallization or lead.
8. N is the maximum number of terminal positions.
9. Braze fillets shall be concave.
10. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
11. Controlling dimension: INCH.

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